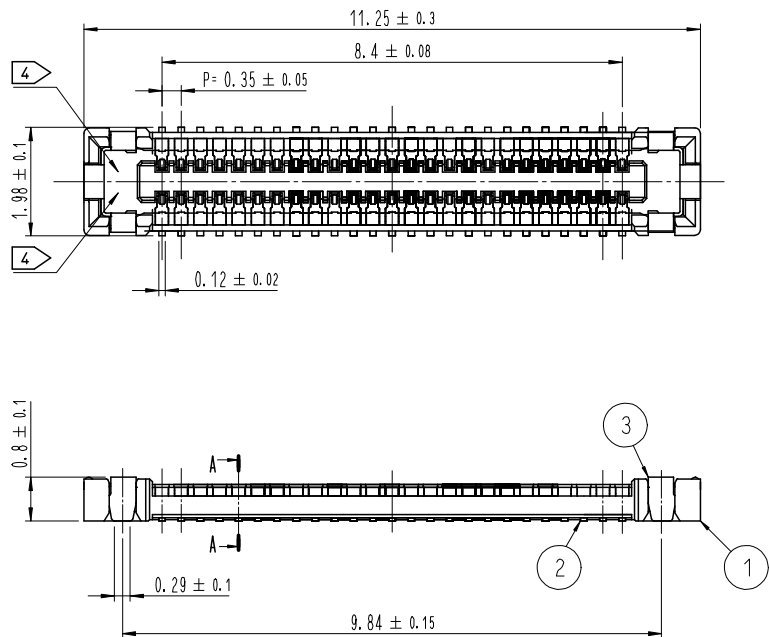
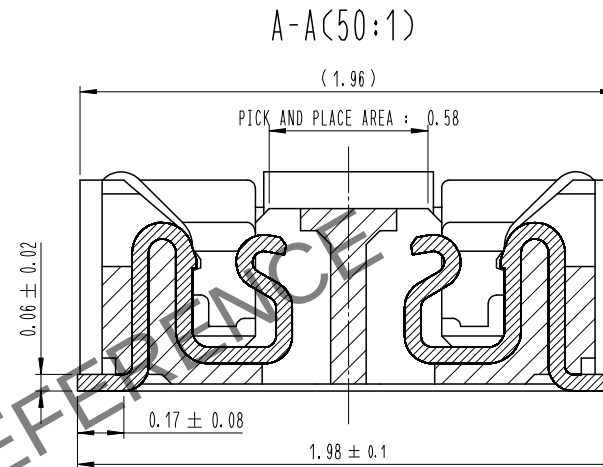


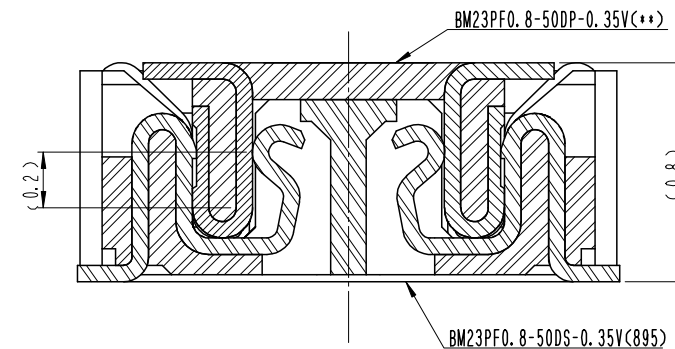


- NOTE
- 1. ALL LEAD CO-PLANARITY SHALL BE 0.08mm MAX.
 - 2. CONTACT PLATING SPECIFICATIONS.
CONTACT AREA : GOLD 0.05 μm MIN.
SMT LEAD : GOLD 0.05 μm MIN.
UNDERPLATING : NICKEL 1 μm MIN.
(SURFACE : SEALING)
 - 3. METAL FITTING PLATING SPECIFICATIONS.
SMT LEAD : GOLD 0.05 μm MIN.
UNDERPLATING : NICKEL 1 μm MIN.
(SURFACE : SEALING)
 - 4. HRS MARK AND CAV NO. IS INDICATED IN APPROX POSITION SHOWN.

△數 COUNT	訂正事項 DESCRIPTION OF REVISIONS	擔當 B Y	檢圖 CHKD	年月日 DATE	△數 COUNT	訂正事項 DESCRIPTION OF REVISIONS	擔當 B Y	檢圖 CHKD	年月日 DATE
△				.	△				.
△				.	△				.
△				.	△				.

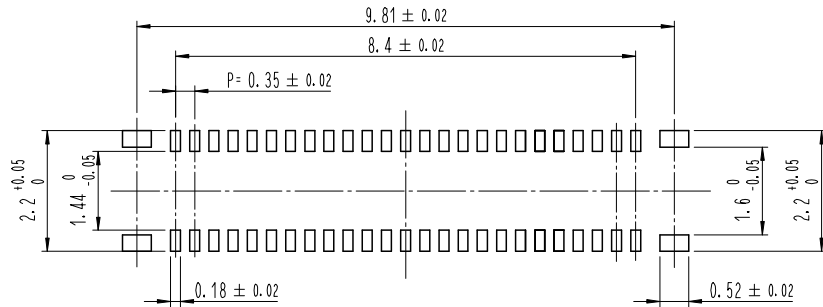


ENGAGEMENT FIGURE (50:1)

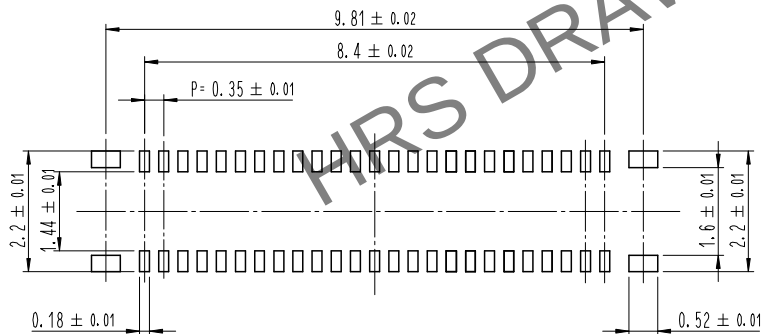


4	PS	CLEAR (EMBOSSED CARRIER TAPE)							
3	PHOSPHOR BRONZE	3		7	PS	CLEAR (REINFORCEMENT COLLAR)			
2	PHOSPHOR BRONZE	2		6	PS	BLACK (PLASTIC REEL)			
1	LCP	UL94 V-0, BLACK		5	POLYESTER	CLEAR (COVER TAPE)			
NO.	MATERIAL	FINISH , REMARKS		NO.	MATERIAL	FINISH , REMARKS			
REMARKS					DRAWN	DESIGNED	CHECKED	APPROVED	RELEASED
					S. H. PARK	S. H. PARK	H. W. JO	H. W. JO	20. 04. 15
					20. 04. 15	20. 04. 15	20. 04. 15	20. 04. 15	
CODE NO. (OLD)		DRAWING NO.			PART NO.	BM23PF0.8-50DS-0.35V(895)			
	SCALE	EDC3-632435-95							
	10:1	 HIROSE KOREA CO., LTD.			CODE NO	CL 6644-0066-2-895			
	UNITS								
						1/3			

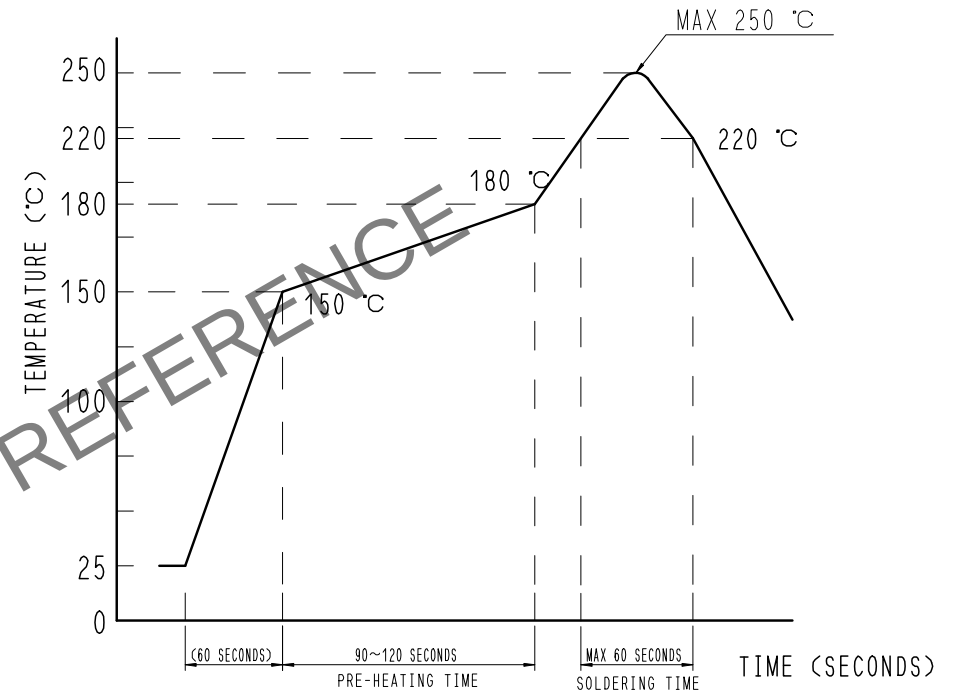
6 RECOMMENDED PCB LAYOUT



RECOMMENDED METAL MASK DIMENSIONS METAL MASK THICKNESS : $100 \mu m$



5 RECOMMENDED REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE.



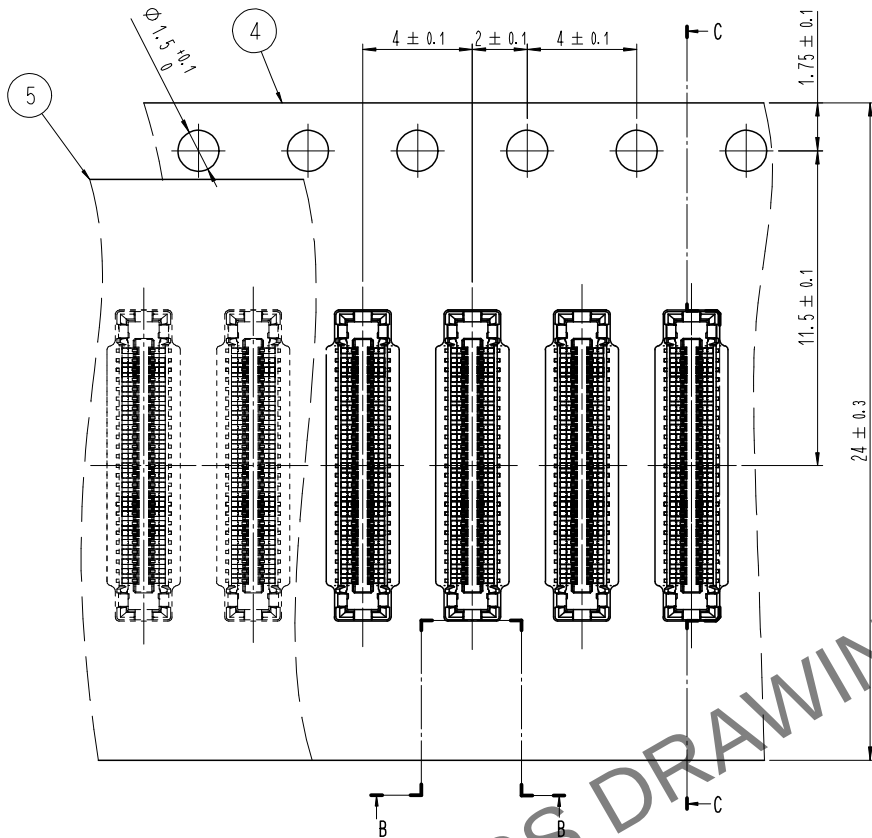
REFLOW METHOD: N_2 REFLOW
 NUMBER OF REFLOW CYCLES: 2 CYCLES MAX.

- 1) REFLOW TIME
 DURATION ABOVE 220°C: 60 SEC MAX.
 (PEAK TEMPERATURE: 250°C MAX)
- 2) PRE-HEAT TIME
 PRE-HEAT TEMPERATURE(MIN): 150°C
 PRE-HEAT TEMPERATURE(MAX): 180°C
 PRE-HEAT TIME: 90~120 SEC.

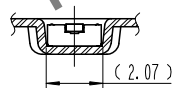
- 5  THIS TEMPERATURE PROFILE IS PER THE CONDITIONS SHOWN ABOVE.
 ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE, PCB SIZE AND
 OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE. THEREFORE,
 A THOROUGH EVALUATION OF MOUNTING CONDITION IS REQUIRED
 PRIOR TO PRODUCTION. TEMPERATURE IS MEASURED AT CONTACT LEAD.
- 6  PLEASE CONTACT US IN CASE YOU WILL MAKE DIFFERENT SETTINGS FROM OUR RECOMMENDATION.

 SCALE 10:1 UNITS mm	DRAWING NO.	EDC3-632435-95	PART NO.	BM23PF0.8-50DS-0.35V(895)
	HIROSE KOREA CO., LTD.		CODE NO.	CL 6644-0066-2-895

EMBOSSED CARRIER TAPE PACKAGING (5:1)

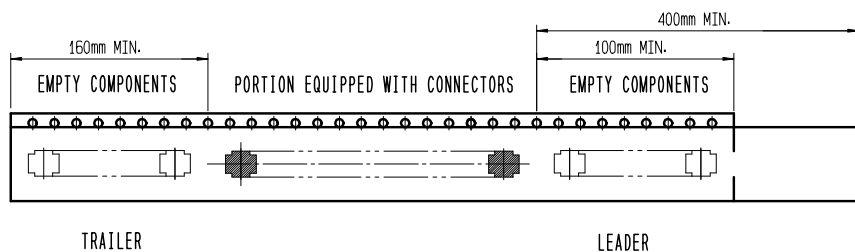


B-B (5:1)

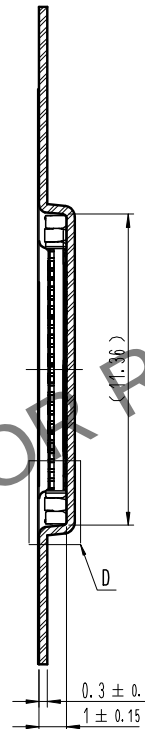


10 TAPING(FREE)

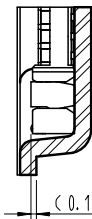
DIRECTION OF UNREELING



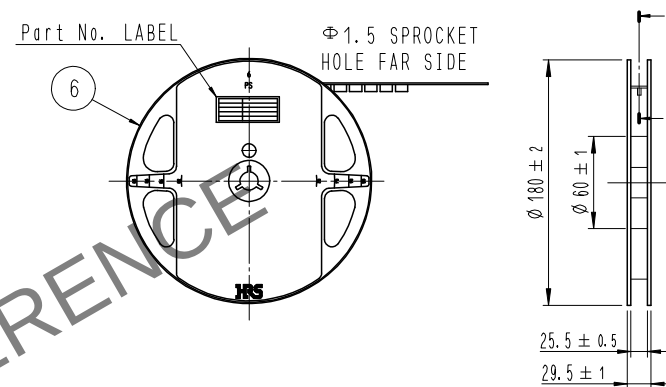
C-C (5:1)



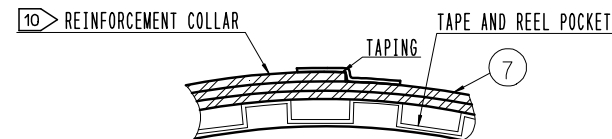
D (10:1)



STYLE AND DIMENTION OF REEL (FREE)



E-E (FREE)



DETAIL OF PART NO. LABEL

SUPPLIER	
QUANTITY	
PART NO.	
CODE NO.	
DATE OF MANUFACTURED	
生産月日	年 月 日
図番	** ** *
品名	BM23PF0. 8-50DS-0. 35V<895>
納入数量	1,000個
納入者	HIROSE KOREA

7 . PER REEL 1,000 CONNECTORS.

8 . THE DIMENSIONS IN PARENTHESES ARE FOR REFERENCE.

9 REFER TO JIS C 0806. IEC-60286-3 (PACKAGING OF COMPONENTS FOR AUTOMATIC HANDLING)

10 AFTER PACKAGING. ROLL 2 METERS OF THE REINFORCEMENT COLLAR TO OUTER CIRCUMFERENCE OF TAPE AND REEL POCKET. AND TAPE DOWN AT THE END THE COLLAR.

DRAWING NO.	EDC3-632435-95	PART NO.	BM23PF0. 8-50DS-0. 35V<895>
SCALE	10:1	CODE NO.	CL 6644-0066-2-895
UNITS	mm		
HRS HIROSE KOREA CO., LTD.			